

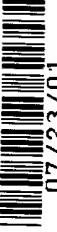
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JC970 U.S. PTO

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PATENT APPLICATION

Assistant Commissioner for Patents  
Box Patent Application  
Washington, D. C. 20231

J1046 U.S. PTO  
09/912103  
07/23/01  


Sir:

Enclosed herewith for filing is the following **utility patent application**:

Applicant(s): Huong Thanh Nguyen  
Michael Scott Barnes  
Li-Qun Xia  
Mehul Naik

Title of Application: SELECTIVE ETCHING OF ORGANOSILICATE FILMS OVER SILICON OXIDE STOP ETCH LAYERS

Pages of specification: 20 (including 3 pages of claims and 1 page of abstract)

Sheets of drawing: 5

Executed on: 7-23-01 Docket No.: 5619/DD/LOW K/JW

PATENT APPLICATION FILING FEE CALCULATION					
	No.	Filed	Less	Rate/Claim	Fee
Total Claims		20	-20	0 x \$18.00	\$ 0.00
Independent Claims		1	- 3	0 x \$80.00	\$ 0.00
				Minimum Filing Fee	\$710.00
				Multiple Dependency Fee (if applicable - \$270.00)	\$ _____
				50% Reduction for Small Entity (Independent Inventor, Non-profit Corporation, or Small Business Concern) - appropriate verified statement attached	- \$ 0.00
				<b>TOTAL FILING FEE</b>	<b>\$710.00</b>

Kindly charge the entire and/or any additional filing fee, as appropriate, to deposit account number **50-1074**. To facilitate that charge, a duplicate copy of this letter is enclosed herewith.

Please direct all correspondence to:  
Patent Counsel  
Applied Materials, Inc.  
3050 Bowers Avenue  
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Santa Clara, CA 95052

Also enclosed herewith for filing in connection with the enclosed application are:

Serial Number      Filing date

Respectfully submitted,

Robert W. Mulcahy, Attorney  
Reg. No. 25,436

**\*\*\*EXPRESS MAIL CERTIFICATION\*\*\***

"Express Mail" mailing label number: **EL661804100US**  
Date of deposit: **7-23-01**

I hereby certify that this patent application and related papers is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to the Assistant Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.

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